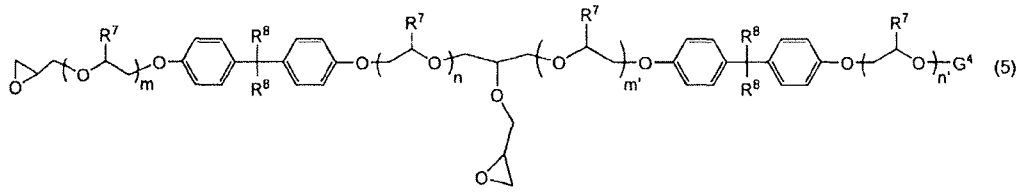
integer of 1 or more and satisfy a relation represented by $3 \leq (m + n) \leq 12$,

[Formula 6]



(5)

wherein R^7 and R^8 each independently represent a hydrogen atom or a methyl group, and G^4 represents a hydrogen atom or a glycidyl group; and m, n, m' and n' are each independently an integer of 1 or more, and satisfy a relation represented by $6 \leq (m + n + m' + n') \leq 20$.

[Claim 6]

The epoxy resin composition according to claim 5, wherein G^4 in the formula (5) is a glycidyl group.

~~[Claim 7]~~

~~An epoxy resin represented by the following formula (1),~~

~~wherein m and n in the formula (1) are each independently an integer of 1 to 11, and satisfy a relation represented by $3 \leq (m + n) \leq 12$; and~~

~~a proportion of the component having m and n satisfying a relation represented by $6 \leq (m + n) \leq 12$ in the epoxy resin is 30 mol% or more and 70 mol% or less.~~

~~[Formula 7]~~

~~$G^1-(OR^1)_m-O-R^2-O-(R^1O)_n-G^2$ (1)~~

wherein m and n are each independently an integer of 1 to 30, R^1 and R^2 each independently represent an aliphatic group having 1 to 12 carbon atoms or a divalent aromatic group, at least one of R^1 and R^2 represents a divalent aromatic group having 6 to 30 carbon atoms, G^1 represents a glycidyl group, and G^2 represents a hydrogen atom or a glycidyl group.

[Claim 8]

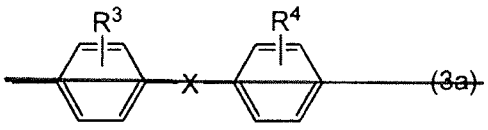
The epoxy resin according to claim 7, wherein a proportion of a component represented by formula (1) with G^2 representing a glycidyl group in the epoxy resin is 10 mol% or more and 100 mol% or less.

[Claim 9]

The epoxy resin according to claim 7 or 8,

wherein R^2 in the formula (1) is any one selected from the group consisting of a phenylene group, a naphthylene group, a biphenylene group and a divalent aromatic group having the structure represented by the following formula (3a):

[Formula 8]



(3a)

wherein R^3 and R^4 each independently represent any one selected from the group consisting of a hydrogen atom, a halogen atom, a hydroxyl group, an alkoxy group having 1 to 12 carbon atoms, a carboxyl group and an alkyl group

~~having 1 to 12 carbon atoms, and X represents any one selected from the group consisting of an alkylene group having 1 to 10 carbon atoms, -O-, -CO-, -COO-, -S-, -SO-, $-SO_2-$ and -S-S-.~~

~~[Claim 10]~~

~~The epoxy resin according to any one of claims 7 to 9, wherein a total chlorine content is 1000 ppm by mass or less.~~

[Claim ~~11~~ 7]

An epoxy resin composition comprising:

the epoxy resin composition according to any one of claims 1 to 6~~, or the epoxy resin according to any one of claims 7 to 10~~; and

a curing agent.

[Claim ~~12~~ 8]

A cured product obtained by curing the epoxy resin composition according to claim ~~11~~ 7.

~~[Claim 13]~~

~~A cured product obtained from the epoxy resin represented by the following formula (1),~~

~~wherein when the cured product is subjected to a cured product measurement at a frequency of 1 Hz with a dynamic viscoelastic measurement apparatus, the cured product satisfies a relation represented by the following mathematical expression (a) and a relation represented by the following mathematical expression (b):~~

~~[Formula 9]~~

~~$G^1-(OR^1)_m-O-R^2-O-(R^1O)_n-G^2$ (1)~~

~~wherein m and n are each independently an integer of 1 to 30, R^1 and R^2 each independently represent an aliphatic group having 1 to 12 carbon atoms or a divalent aromatic group, at least one of R^1 and R^2 represents a divalent aromatic group having 6 to 30 carbon atoms, G^1 represents a glycidyl group, and G^2 represents a hydrogen atom or a glycidyl group,~~

~~$E'/(273 + T^1/3) < 8.5$ ... (a)~~

~~wherein T^1 is a obtained peak top temperature of a loss tangent, and E'(MPa) is a storage modulus measured at 30°C;~~

~~$E'(T^1 - 20) > 10 \times E'(T^1 + 20)$ ... (b)~~

~~wherein $E'(T^1 - 20)$ is a storage modulus measured at $(T^1 - 20)$°C, and $E'(T^1 + 20)$ is a storage modulus measured at $(T^1 + 20)$°C.~~

~~[Claim 14]~~

~~The cured product according to claim 13,~~

~~wherein the cured product further satisfies a relation represented by the following mathematical expression (c), and a relation represented by the following mathematical expression (d):~~

~~$E'/(273 + T^1/3) < 7$ ... (c)~~

~~wherein E' is the storage modulus measured at 30°C, and T^1 is the obtained peak top temperature of the loss tangent.~~

$E'(T^1 - 20) > 20 \times E'(T^1 + 20)$ ... (d)

wherein E' is the storage modulus measured at 30°C, and T^1 is the obtained peak top temperature of the loss tangent.

[Claim 15]

An electronic part comprising the cured product according to any one of claims 12 to 14.